

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

08 Feb 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16098

TITLE: Final Notification of ISMF Wafer Fab Qualification for Schottky Rectifier Products (Phase 2)

PROPOSED FIRST SHIP DATE: 08 May 2008

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

AFFECTED PRODUCT DIVISION(S): Automotive & Power Regulation Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION: Contact your local ON Semiconductor Sales Office or Mark Thomas Mark.Thomas@onsemi.com

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers<<u>laura.rivers@onsemi.com</u>>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the second FPCN to IPCN 16006 that announced the ON Semiconductor is adding wafer fabrication capacity for the Schottky Rectifier products listed herein at the ISMF wafer fab in Seremban, Malaysia. The ISMF facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor since 1998. Several existing technologies within ON Semiconductor's product families are currently sourced from ISMF, including Zener diodes, Small Signal transistors and diodes, and USB array filter products.

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RELIABILITY DATA SUMMARY:

MBRS260T3

MSL1 @ 260C		0/960
MSL performed before TC, H3TRB, A	AC and IOL	
HTRB Ta=90C, Vr=48V	1008 hours	0/240
HTSL Ta=150C	1008 hours	0/240
Temp Cycle		
Ta = -65/150C	1000 cycles	0/240
Autoclave		
Ta = 121C, RH=100% psig ~14.7	96 hours	0/240
H3TRB Ta=85C, RH=85% Vr=48V	1008 hours	0/240
IOL Ta=25C, Tjmax=100		
Ton=Toff=2minutes	15000 cycles	0/240
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MBRB20200CT

HTRB Ta=90C, Vr=160V	1008 hours	0/240
HTSL Ta=150C	1008 hours	0/240
Temp Cycle		
Ta = -65/150C	1000 cycles	0/240
Autoclave		
Ta = 121C, RH=100% psig ~14.7	96 hours	0/240
H3TRB Ta=85C, RH=85% Vr=100V	1008 hours	0/240
IOL Ta=25C, Tjmax=100		
Ton=Toff=3.5minutes	8572 cycles	0/240

ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes in electrical characteristics; product performance meets data sheet specifications. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

Devices using die sourced from ISMF fab may be produced starting with date code 08 20

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AFFECTED DEVICE LIST:

1N5818G 1N5818RLG 1N5819G 80SQ045NG MBR0530T1 MBR0530T1G MBR0530T3G MBR130T1 MBR130T1G MBR130T3G MBR140SFT1G MBR140SFT3G MBR20200CT MBR20200CTG MBR20L45CTG MBR2535CTL MBR30H30CTG MBR30L45CTG MBR40250G MBR40250TG MBR40L45CTG MBR60L45CTG MBR60L45WTG MBRA140T3 MBRA140T3G MBRA340T3G MBRB20200CT MBRB20200CTG MBRB20200CTT4 MBRB20200CTT4G MBRB2535CTLG MBRB2535CTLT4 MBRB2535CTLT4G MBRB3030CTLG MBRB30H30CT-1G MBRC20200CTWP MBRC2535CTLWP MBRC835LWP MBRD1035CTLG MBRD835LG MBRD835LT4 MBRD835LT4G MBRF20200CT MBRF20200CTG MBRF20L45CTG MBRF30L45CTG MBRF40250TG MBRM140T1 MBRM140T1G MBRM140T3 MBRM140T3G MBRS120T3

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MBRS120T3G MBRS130T3G MBRS140T3 MBRS140T3G MBRS1540T3G MBRS2040LT3 MBRS2040LT3G MBRS240LT3 MBRS240LT3G MBRS3200T3 MBRS3200T3G MBRS3201T3G MBRS320T3 MBRS320T3G MBRS330T3G MBRS340T3 MBRS340T3G MBRS4201T3G MBRS540T3 MBRS540T3G SBRA140T3G SBRS5633-3T3 SS22T3G SS24T3 SS24T3G